

N-Channel Enhancement Mode Power MOSFET

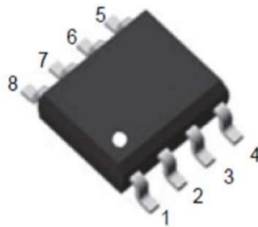
Features

- $V_{DS} = 20V$, $I_D = 12A$
 $R_{DS(ON)} < 6 m\Omega @ V_{GS} = 4.5V$
 $R_{DS(ON)} < 8 m\Omega @ V_{GS} = 2.5V$

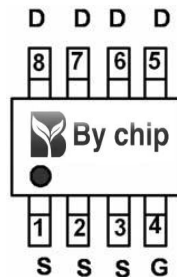
General Features

- Advanced Trench Technology
- Provide Excellent $R_{DS(ON)}$ and Low Gate Charge
- Lead Free and Green Available

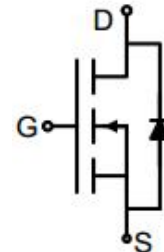
100% UIS TESTED!
 100% ΔV_{ds} TESTED!



SOP-8



pin assignment



Schematic diagram

Absolute Maximum Ratings ($T_A = 25^\circ C$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V_{DS}	20	V
Gate-Source Voltage	V_{GS}	± 12	V
Drain Current-Continuous	I_D	12	A
Drain Current-Continuous($T_A = 100^\circ C$)	$I_D(100^\circ C)$	8	A
Pulsed Drain Current	I_{DM}	40	A
Maximum Power Dissipation	P_D	2.5	W
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55 To 150	$^\circ C$

Thermal Characteristic

Thermal Resistance, Junction-to-Ambient ^(Note 2)	$R_{\theta JA}$	50	$^\circ C/W$
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Electrical Characteristics ($T_A=25^{\circ}\text{C}$ unless otherwise noted)

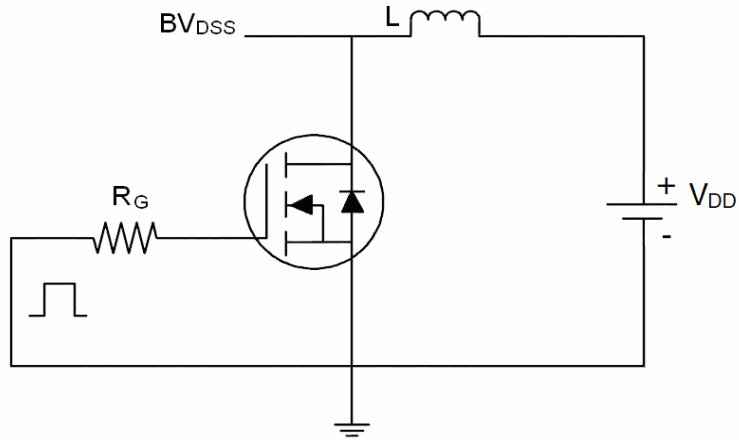
Parameter	Symbol	Condition	Min	Typ	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V, I_D=250\mu A$	20	-	-	V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=20V, V_{GS}=0V$	-	-	1	μA
Gate-Body Leakage Current	I_{GSS}	$V_{GS}=\pm 12V, V_{DS}=0V$	-	-	± 100	nA
On Characteristics (Note 3)						
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	0.5		2.0	V
Drain-Source On-State Resistance	$R_{DS(ON)}$	$V_{GS}=4.5V, I_D=6A$	-		6	m Ω
		$V_{GS}=2.5V, I_D=5A$			8	m Ω
Forward Transconductance	g_{FS}	$V_{DS}=10V, I_D=6A$	20	-	-	S
Dynamic Characteristics (Note 4)						
Input Capacitance	C_{iss}	$V_{DS}=10V, V_{GS}=0V,$ $F=1.0\text{MHz}$	-	2000	-	PF
Output Capacitance	C_{oss}		-	402	-	PF
Reverse Transfer Capacitance	C_{rss}		-	170	-	PF
Switching Characteristics (Note 4)						
Turn-on Delay Time	$t_{d(on)}$	$V_{DD}=10V, I_D=6A$ $V_{GS}=4.5V, R_{GEN}=1\Omega$	-	25	-	nS
Turn-on Rise Time	t_r		-	15	-	nS
Turn-Off Delay Time	$t_{d(off)}$		-	25	-	nS
Turn-Off Fall Time	t_f		-	15	-	nS
Total Gate Charge	Q_g	$V_{DS}=10V, I_D=6A,$ $V_{GS}=10V$	-	42	-	nC
Gate-Source Charge	Q_{gs}		-	10.8	-	nC
Gate-Drain Charge	Q_{gd}		-	9.2	-	nC
Drain-Source Diode Characteristics						
Diode Forward Voltage (Note 3)	V_{SD}	$V_{GS}=0V, I_S=6A$	-	-	1.2	V
Diode Forward Current (Note 2)	I_S		-	-	12	A

Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, $t \leq 10$ sec.
3. Pulse Test: Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 2\%$.
4. Guaranteed by design, not subject to production

Test Circuit

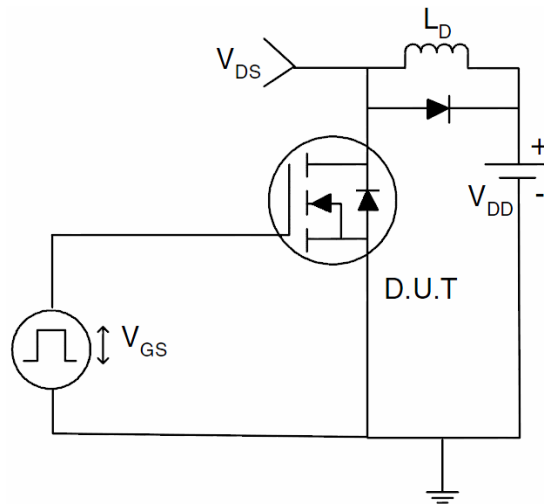
1) E_{AS} Test Circuits



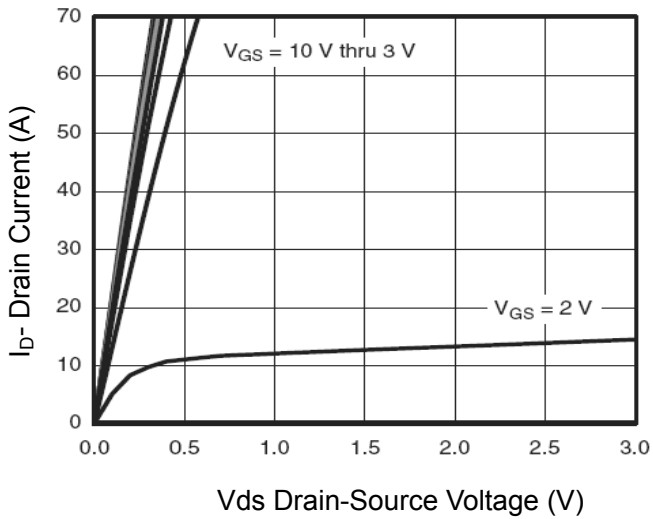
2) Gate Charge Test Circuit



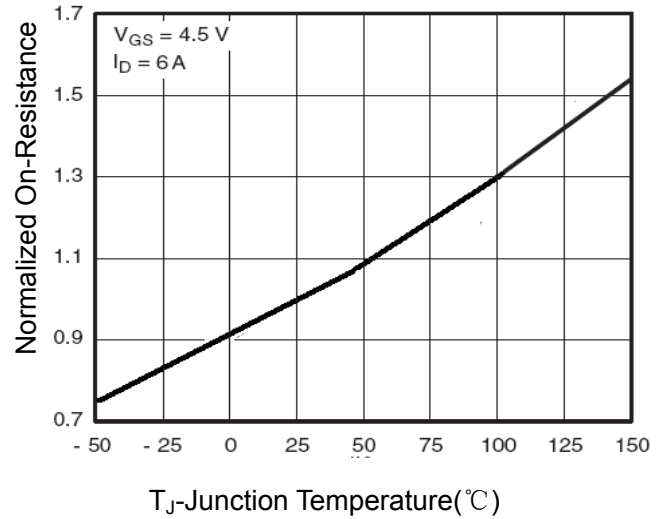
3) Switch Time Test Circuit



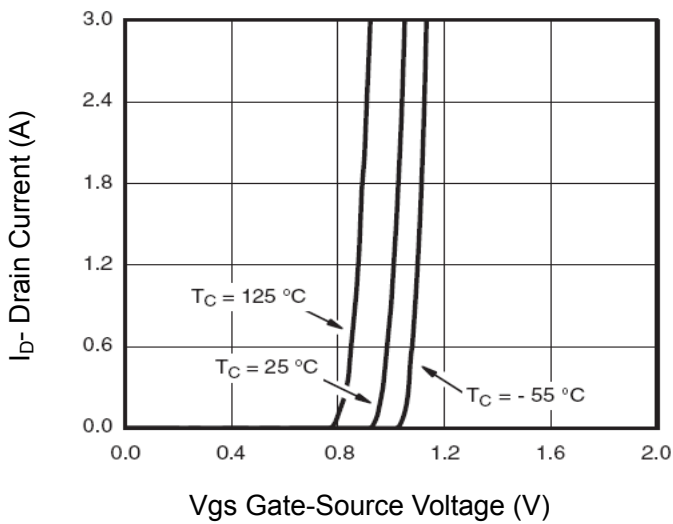
Typical Electrical and Thermal Characteristics (Curves)



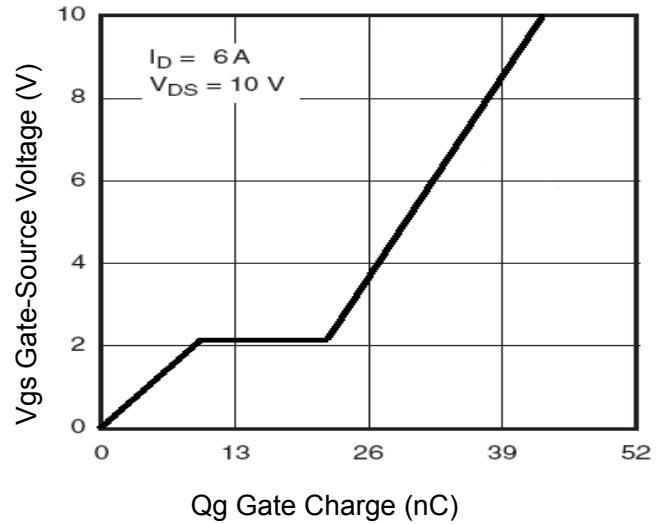
Vds Drain-Source Voltage (V)
Figure 1 Output Characteristics



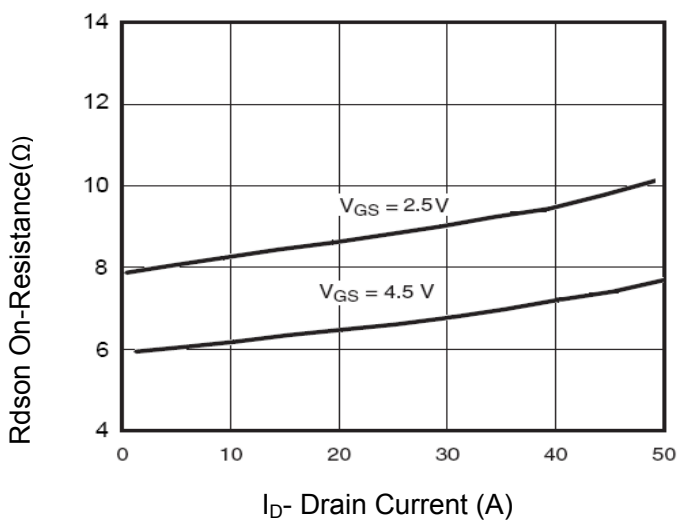
T_J -Junction Temperature(°C)
Figure 4 Rdson-Junction Temperature



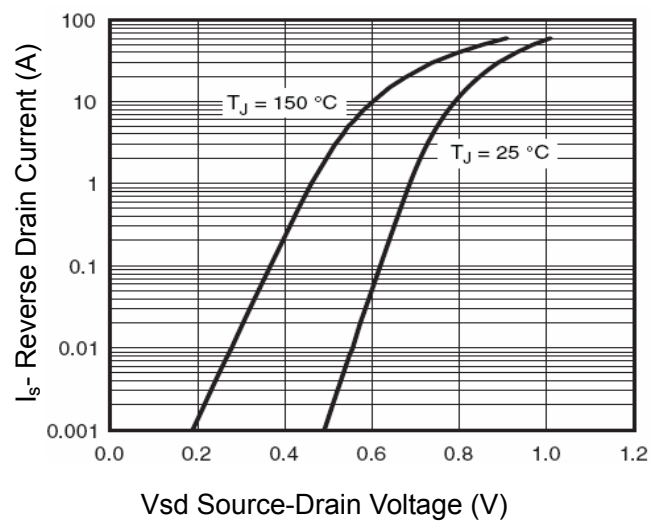
Vgs Gate-Source Voltage (V)
Figure 2 Transfer Characteristics



Qg Gate Charge (nC)
Figure 5 Gate Charge



I_D - Drain Current (A)
Figure 3 Rdson- Drain Current



Vsd Source-Drain Voltage (V)
Figure 6 Source- Drain Diode Forward

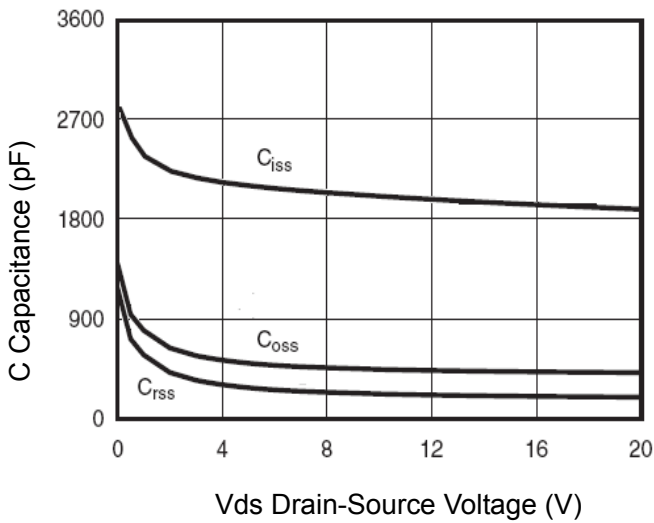


Figure 7 Capacitance vs Vds

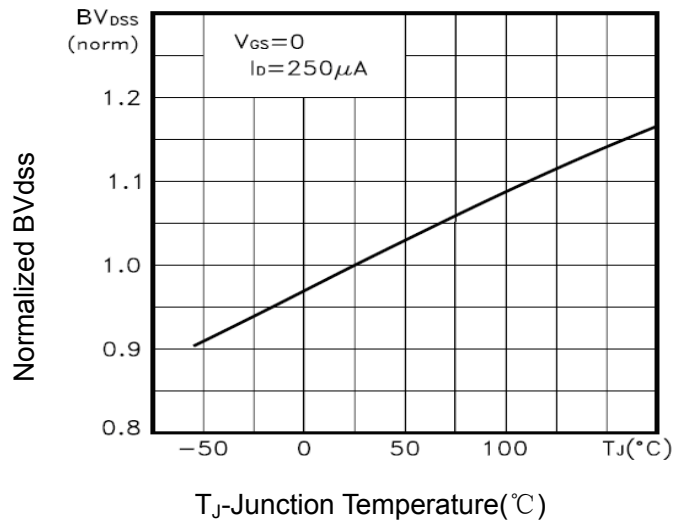


Figure 9 BV_{DSS} vs Junction Temperature

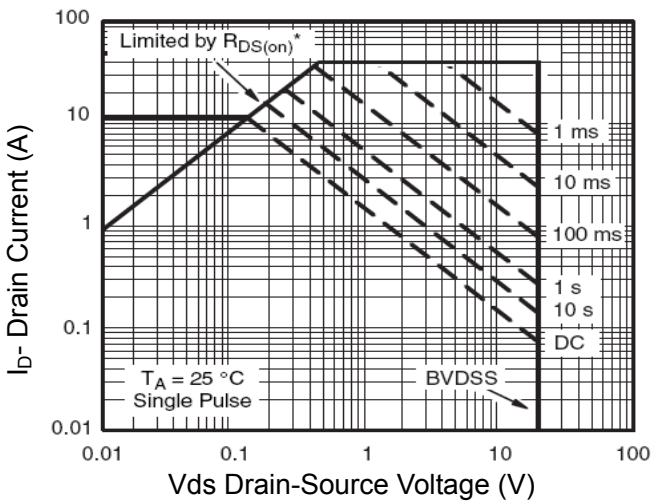


Figure 8 Safe Operation Area

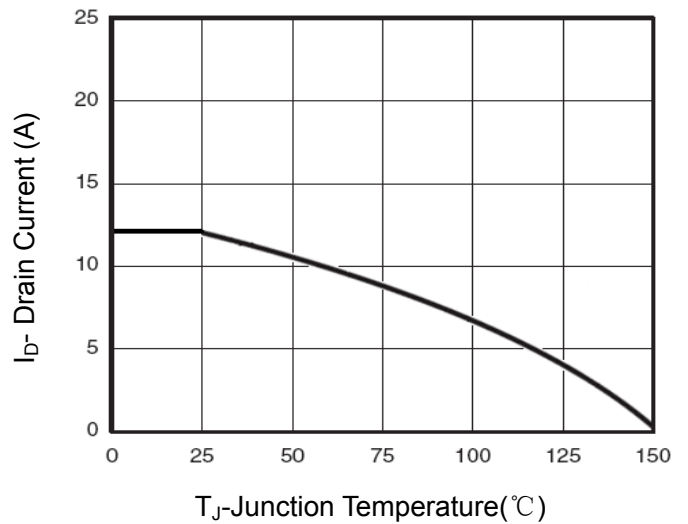


Figure 10 Current vs Junction Temperature

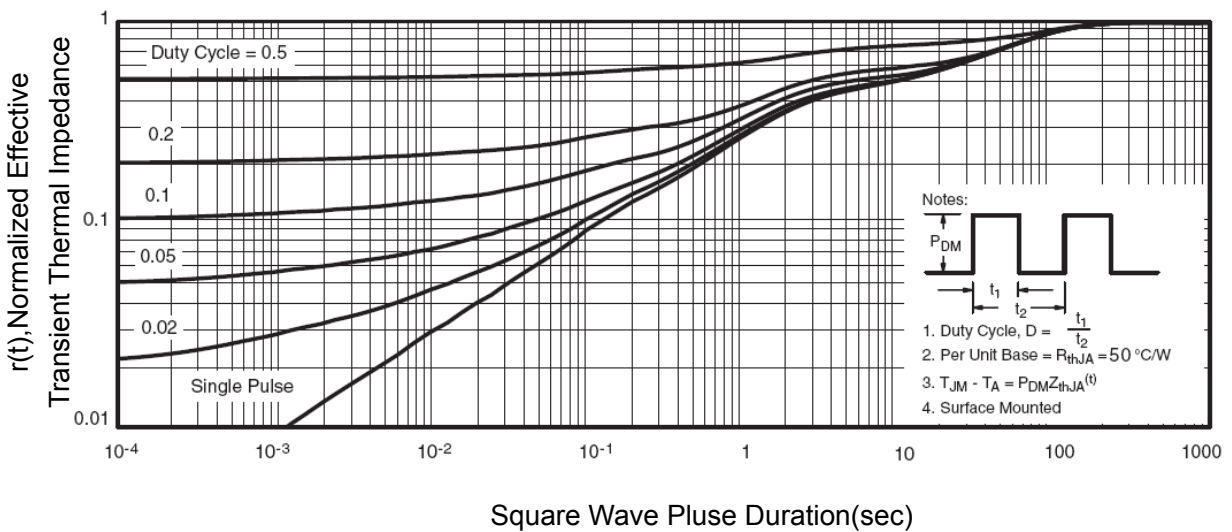


Figure 11 Normalized Maximum Transient Thermal Impedance